

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: F0007-01 DATE: 08/04/00 Product Affected: FIFO Dual Die Products in PA 56 Package (list of devices attached) Manufacturing Location Affected: ALL Date Effective: 09/04/00		MEANS OF DISTINGUISHING CHANGED DEVICES: Product Mark Back Mark Varning label on dry-pack Date Code Other			
Contact: Dasharath Patel Title: Quality Assurance Manag	zer	Attachment:	Yes	□ No	
Phone #: (408) 330-1488					
Fax #: (408) 330-1450		Samples: Availab	ole upon request.		
E-mail: dasharath.patel@idt.com					
DESCRIPTION AND PURPOSE OF CHANGE: Die Technology Wafer Fabrication Process Packaging - introduction of dry-pack requirement, due to change in moisture Assembly Process Packaging - introduction of dry-pack requirement, due to change in moisture Equipment J-STD-020A, which requires usage of a higher reflow temperature of 240C). Level III Material was determined to be more appropriate for customer shipment. Testing Please see attachment for details of products affected. Data Sheet Other					
RELIABILITY/QUALIFICATION SUMMARY: Available upon request.					
CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.					
Customer:	□	Approval for s	hipments prior to	effective date.	
Name/Date:	E-I	Mail Address:			
Title:	Pho	one# /Fax# :			
CUSTOMER COMMENTS:					
IDT ACKNOWLEDGMENT OF RECEIPT:					
RECD. BY:		DATE:		_	



PRODUCT/PROCESS CHANGE NOTICE (PCN) ATTACHMENT - PCN #: F0007-01

PCN Summary PCN Type:	Packaging/Label/Device Marking Change
Commodity	FIFO Dual Die in PA 56 Package Type
Forecast or Execute	Execute
Planned or Unplanned	Unplanned
Data Sheet Change	N/A
Detail of Change	Moisture classification will be revised from Level I to Level III (as specified by J-STD-020A), for the following dual die devices in the PA 56 package : 7280, 7281, 7282, 7283, 7284, 7285 72V81, 72V82, 72V83, 72V84, 72V85
	This reclassification was performed using the new reflow temperature of 240C, specified by J-STD-020A, and will be applicable to all speed grades of these products.

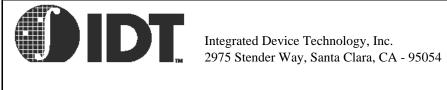
Conversion schedule (Estimated)

Sample Availability

Production Shipments

Immediate

9/4/00



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